

# LC 3 mm (T1) LED, Diffused Low Current LED

LS 3369, LY 3369, LG 3369



## Besondere Merkmale

- **Gehäusotyp:** eingefärbtes, diffuses 3 mm (T1) Gehäuse
- **Besonderheit des Bauteils:** hohe Lichtstärke bei kleinen Strömen; Lötspieße mit Aufsetzebene
- **Wellenlänge:** 628 nm (super-rot), 587 nm (gelb), 570 nm (grün)
- **Abstrahlwinkel:** 60°
- **Technologie:** GaAlP
- **optischer Wirkungsgrad:** 2 lm/W
- **Gruppierungsparameter:** Lichtstärke
- **Lötmethode:** Wellenlöten (TTW)
- **Verpackung:** Schüttgut, gegurtet lieferbar

## Anwendungen

- optischer Indikator
- Hinterleuchtung (LCD, Schalter, Tasten, Displays, Werbebeleuchtung, Allgemeinbeleuchtung)
- Innenbeleuchtung im Automobilbereich (z.B. Instrumentenbeleuchtung, u.ä.)

## Features

- **package:** colored, diffused 3 mm (T1) package
- **feature of the device:** high luminous intensity at low currents; solder leads with stand-off
- **wavelength:** 628 nm (super-red), 587 nm (yellow), 570 nm (green)
- **viewing angle:** 60°
- **technology:** GaAlP
- **optical efficiency:** 2 lm/W
- **grouping parameter:** luminous flux
- **soldering methods:** TTW soldering
- **packing:** bulk, available taped on reel

## Applications

- optical indicators
- backlighting (LCD, switches, keys, displays, illuminated advertising, general lighting)
- interior automotive lighting (e.g. dashboard backlighting, etc.)

Typ Type	Emissionsfarbe Color of Emission	Gehäusefarbe Color of Package	Lichtstärke Luminous Intensity $I_F = 2 \text{ mA}$ $I_V$ (mcd)	Bestellnummer Ordering Code
LS 3369-EH LS 3369-GK	super-red	red diffused	0.71 ... 4.50 1.80 ... 11.2	Q62703Q1748 Q62703Q3821
LY 3369-EH LY 3369-FJ	yellow	yellow diffused	0.71 ... 4.50 1.12 ... 7.10	Q62703Q1749 Q62703Q3822
LG 3369-EH LG 3369-FJ	green	green diffused	0.71 ... 4.50 1.12 ... 7.10	Q62703Q1750 Q62703Q3823

*Anm.: Die Standardlieferform von Serientypen beinhaltet eine untere bzw. eine obere Familiengruppe oder mindestens zwei Einzelgruppen.  
In einer Verpackungseinheit / Gurt ist immer nur eine Helligkeitsgruppe enthalten.  
Die technologiebedingte Helligkeits-Streuung der heutigen LED-Herstellprozesse über einen längeren Fertigungszeitraum (Halbleitermaterial - Chipherstellung - Montageprozess) erlaubt keine Zusage einer einzelnen Helligkeitsgruppe. Daher müssen mindestens zwei Helligkeitsgruppen vorgesehen werden!*

*Note: The standard shipping format for serial types includes a lower or upper family group or at least two individual groups.  
No packing unit / tape ever contains more than one luminous intensity group.  
Luminosity variations caused by the technology used in current LED manufacturing processes over a protracted manufacturing period (semiconductor material - chip fabrication - assembly process) mean that it is not possible to assign LEDs to a single luminous intensity group. For this reason at least two luminous intensity groups must be provided!*

**Grenzwerte**  
**Maximum Ratings**

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Betriebstemperatur Operating temperature range	$T_{op}$	- 55 ... + 100	°C
Lagertemperatur Storage temperature range	$T_{stg}$	- 55 ... + 100	°C
Sperrschichttemperatur Junction temperature	$T_j$	+ 100	°C
Durchlassstrom Forward current ( $T_A=25^\circ\text{C}$ )	$I_F$	7.5	mA
Stoßstrom Surge current $t \leq 10 \mu\text{s}, D = 0.005, T_A=25^\circ\text{C}$	$I_{FM}$	0.15	A
Sperrspannung <sup>1)</sup> Reverse voltage ( $T_A=25^\circ\text{C}$ )	$V_R$	12	V
Leistungsaufnahme Power consumption ( $T_A=25^\circ\text{C}$ )	$P_{tot}$	20	mW
Wärmewiderstand <sup>2)</sup> Thermal resistance Sperrschicht/Umgebung <sup>3)</sup> Junction/ambient <sup>3)</sup> Sperrschicht/Löt看pad Junction/solder point Minimale Beinchenlänge Minimum lead length	$R_{th JA}$  $R_{th JS}$	400  180	K/W  K/W

<sup>1)</sup> für kurzzeitigen Betrieb geeignet / suitable for short term application

<sup>2)</sup>  $R_{th}$  erhöht sich um 13 K/W pro mm Beinchenlänge.  
Each additional 1 mm of lead length increases  $R_{th}$  by 13 K/W.

<sup>3)</sup> Montage auf PC-Board FR 4 (Padgröße  $\geq 16 \text{ mm}^2$ )  
mounted on PC board FR 4 (pad size  $\geq 16 \text{ mm}^2$ )

**Kennwerte ( $T_A = 25\text{ °C}$ )**  
**Characteristics**

Bezeichnung Parameter	Symbol Symbol	Werte Values			Einheit Unit
		LS	LY	LG	
Wellenlänge des emittierten Lichtes (typ.) Wavelength at peak emission $I_F = 2\text{ mA}$	$\lambda_{\text{peak}}$	635	586	572	nm
Dominantwellenlänge <sup>1)</sup> (typ.) Dominant wavelength $I_F = 2\text{ mA}$	$\lambda_{\text{dom}}$	628	587	570	nm
Spektrale Bandbreite bei 50 % $I_{\text{rel max}}$ (typ.) Spectral bandwidth at 50 % $I_{\text{rel max}}$ $I_F = 2\text{ mA}$	$\Delta\lambda$	45	45	25	nm
Abstrahlwinkel bei 50 % $I_V$ (Vollwinkel) (typ.) Viewing angle at 50 % $I_V$	$2\phi$	60	60	60	Grad deg.
Durchlassspannung <sup>2)</sup> (typ.) Forward voltage $I_F = 2\text{ mA}$	$V_F$ $V_F$	1.8 2.5	2.0 2.6	1.9 2.5	V V
Sperrstrom (typ.) Reverse current $V_R = 12\text{ V}$	$I_R$ $I_R$	0.01 10	0.01 10	0.01 10	$\mu\text{A}$ $\mu\text{A}$
Temperaturkoeffizient von $\lambda_{\text{peak}}$ (typ.) Temperature coefficient of $\lambda_{\text{peak}}$ $I_F = 2\text{ mA}; -10\text{ °C} \leq T \leq 100\text{ °C}$	$TC_{\lambda_{\text{peak}}}$	0.11	0.10	0.11	nm/K
Temperaturkoeffizient von $\lambda_{\text{dom}}$ (typ.) Temperature coefficient of $\lambda_{\text{dom}}$ $I_F = 2\text{ mA}; -10\text{ °C} \leq T \leq 100\text{ °C}$	$TC_{\lambda_{\text{dom}}}$	0.07	0.07	0.07	nm/K
Temperaturkoeffizient von $V_F$ (typ.) Temperature coefficient of $V_F$ $I_F = 2\text{ mA}; -10\text{ °C} \leq T \leq 100\text{ °C}$	$TC_V$	- 2.0	- 1.6	- 1.9	mV/K
Optischer Wirkungsgrad (typ.) Optical efficiency $I_F = 2\text{ mA}$	$\eta_{\text{opt}}$	2	2	2	lm/W

<sup>1)</sup> Wellenlängen werden mit einer Stromeinprägedauer von 25 ms und einer Genauigkeit von  $\pm 1\text{ nm}$  ermittelt.  
Wavelengths are tested at a current pulse duration of 25 ms and a tolerance of  $\pm 1\text{ nm}$ .

<sup>2)</sup> Spannungswerte werden mit einer Stromeinprägedauer von 1 ms und einer Genauigkeit von  $\pm 0,1\text{ V}$  ermittelt.  
Voltages are tested at a current pulse duration of 1 ms and a tolerance of  $\pm 0.1\text{ V}$ .

**Helligkeits-Gruppierungsschema**  
**Luminous Intensity Groups**

<b>Lichtgruppe</b> <b>Luminous Intensity Group</b>	<b>Lichtstärke</b> <b>Luminous Intensity</b> <b>I<sub>v</sub> (mcd)</b>
E	0.71 ... 1.12
F	1.12 ... 1.80
G	1.80 ... 2.80
H	2.80 ... 4.50
J	4.50 ... 7.10
K	7.10 ... 11.20

Helligkeitswerte werden mit einer Stromeinprägedauer von 25 ms und einer Genauigkeit von ±11 % ermittelt.  
 Luminous intensity is tested at a current pulse duration of 25 ms and a tolerance of ±11 %.

**Gruppenbezeichnung auf Etikett**  
**Group Name on Label**

Beispiel: J  
 Example: J

**Lichtgruppe**  
**Luminous Intensity Group**

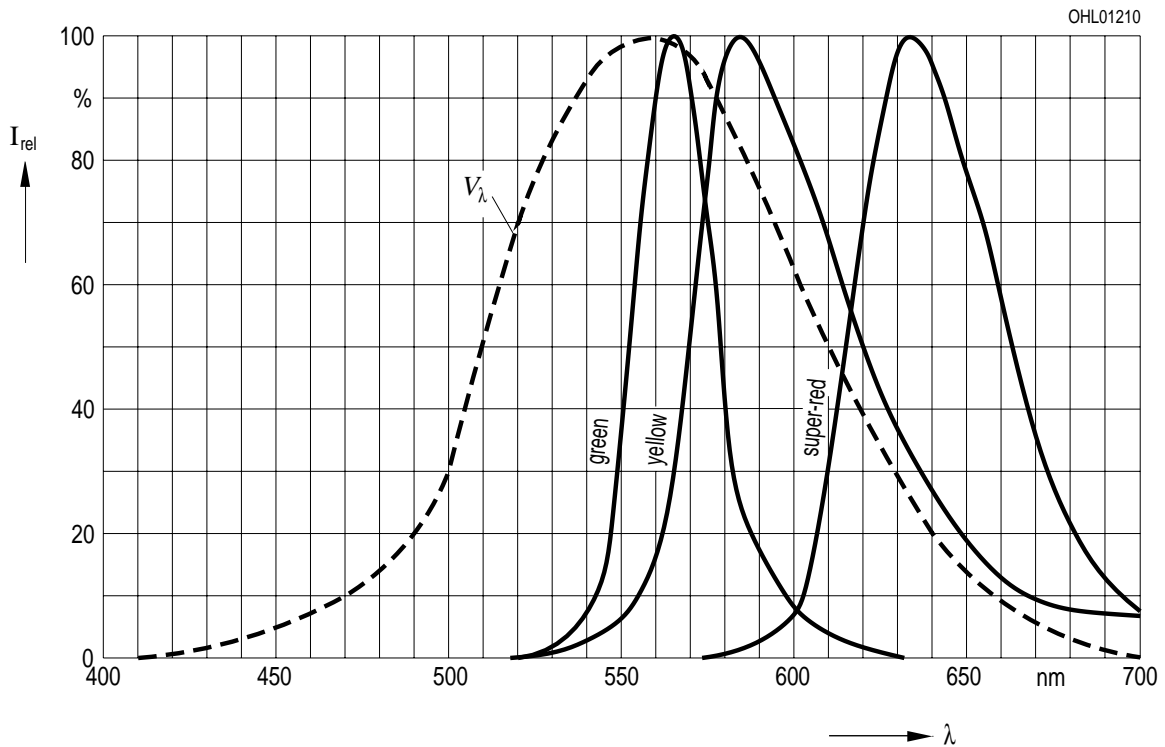
J

Relative spektrale Emission  $I_{rel} = f(\lambda)$ ,  $T_A = 25\text{ °C}$ ,  $I_F = 2\text{ mA}$

**Relative Spectral Emission**

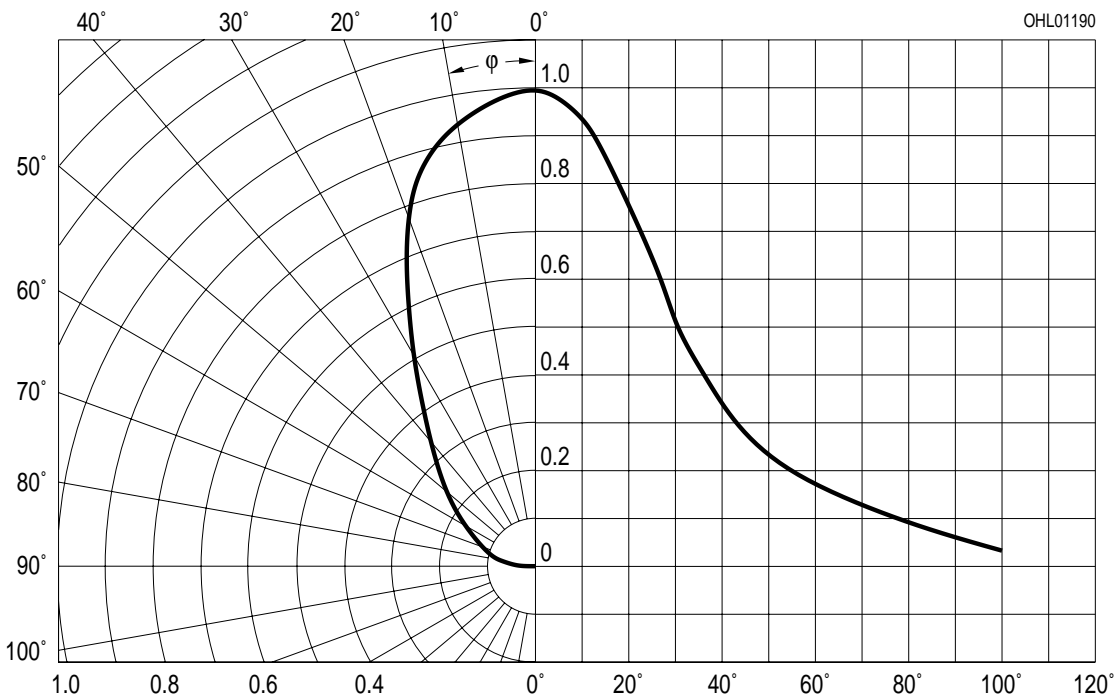
$V(\lambda)$  = spektrale Augenempfindlichkeit

Standard eye response curve



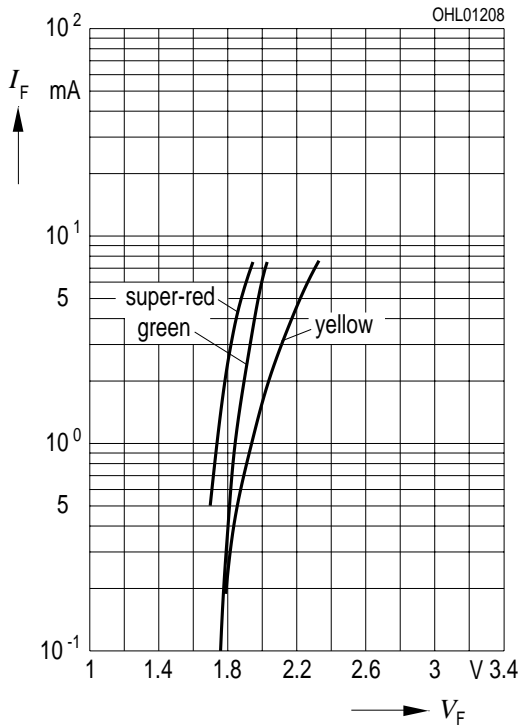
Abstrahlcharakteristik  $I_{rel} = f(\varphi)$

**Radiation Characteristic**



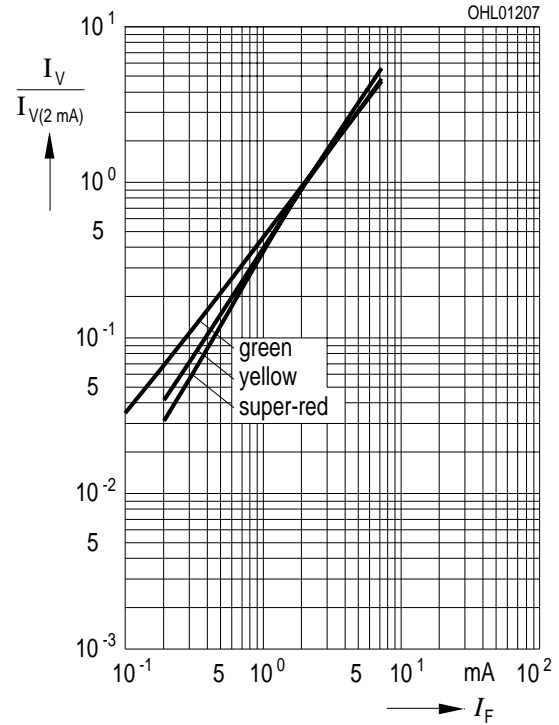
**Durchlassstrom  $I_F = f(V_F)$**   
**Forward Current**

$T_A = 25\text{ }^\circ\text{C}$

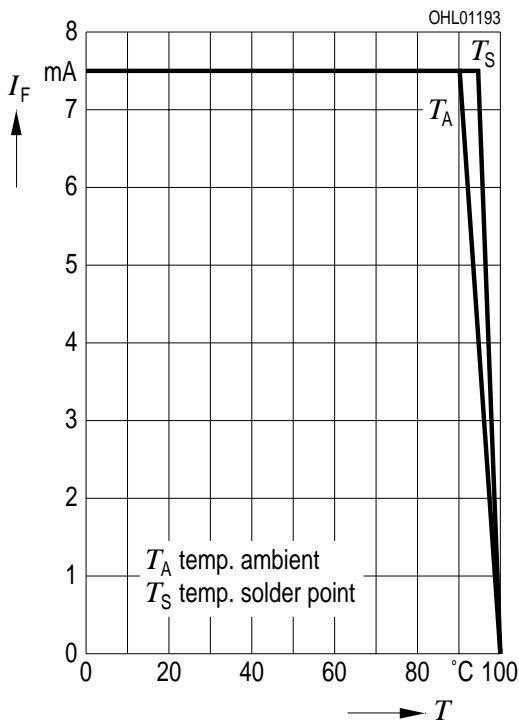


**Relative Lichtstärke  $I_V/I_{V(2\text{ mA})} = f(I_F)$**   
**Relative Luminous Intensity**

$T_A = 25\text{ }^\circ\text{C}$

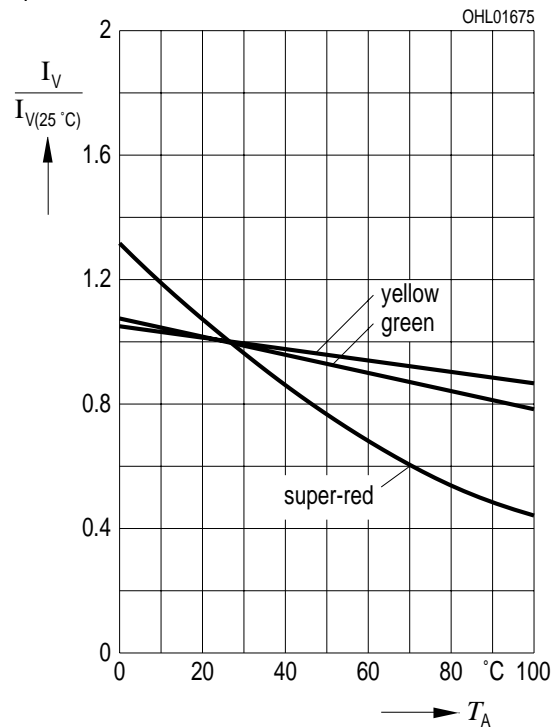


**Maximal zulässiger Durchlassstrom  $I_F = f(T)$**   
**Max. Permissible Forward Current**



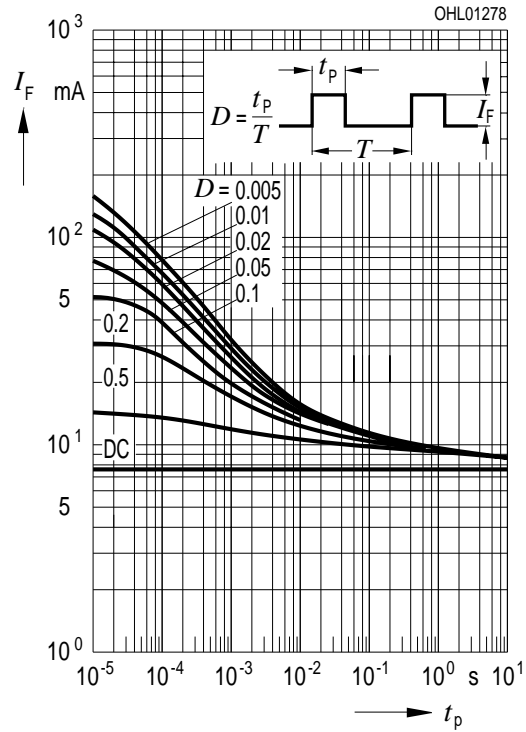
**Relative Lichtstärke  $I_V/I_{V(25\text{ }^\circ\text{C})} = f(T_A)$**   
**Relative Luminous Intensity**

$I_F = 2\text{ mA}$



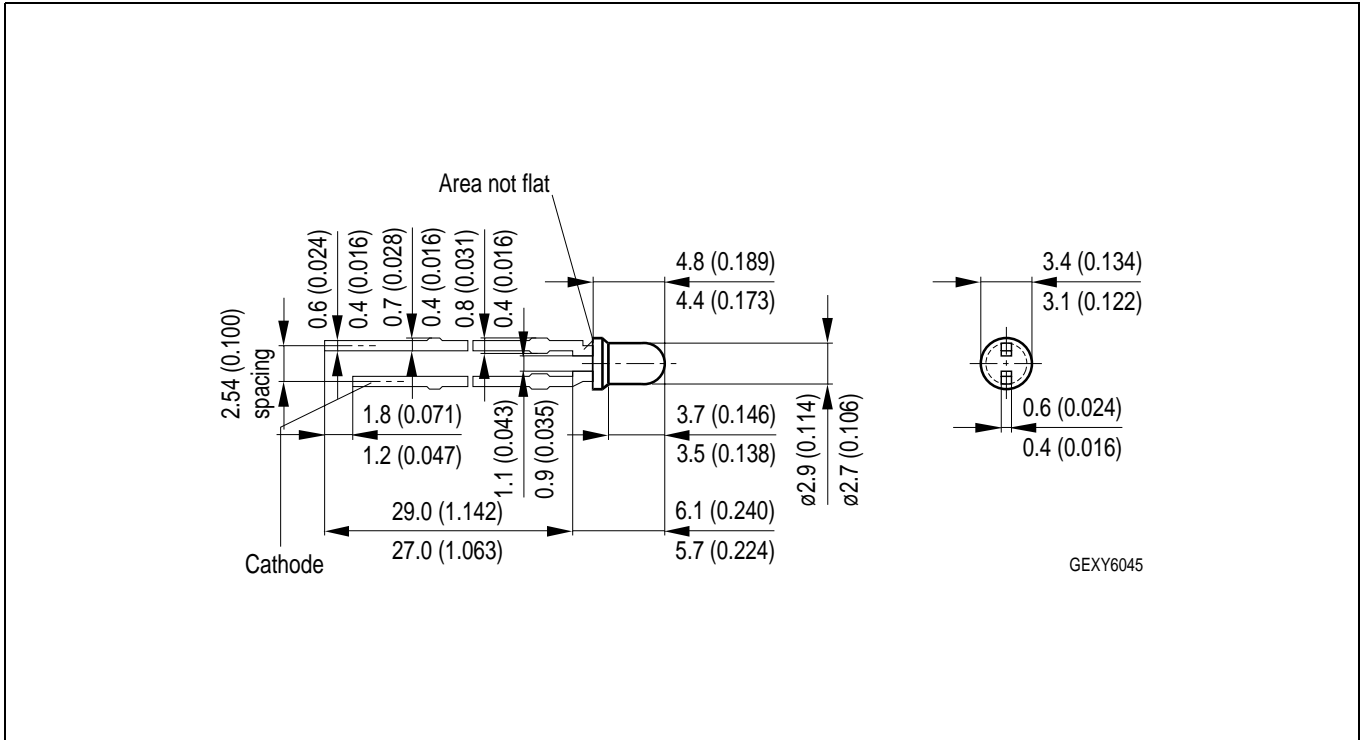
**Zulässige Impulsbelastbarkeit  $I_F = f(t_p)$**   
**Permissible Pulse Handling Capability**

Duty cycle  $D =$  parameter,  $T_A = 25\text{ °C}$





**Maßzeichnung  
Package Outlines**

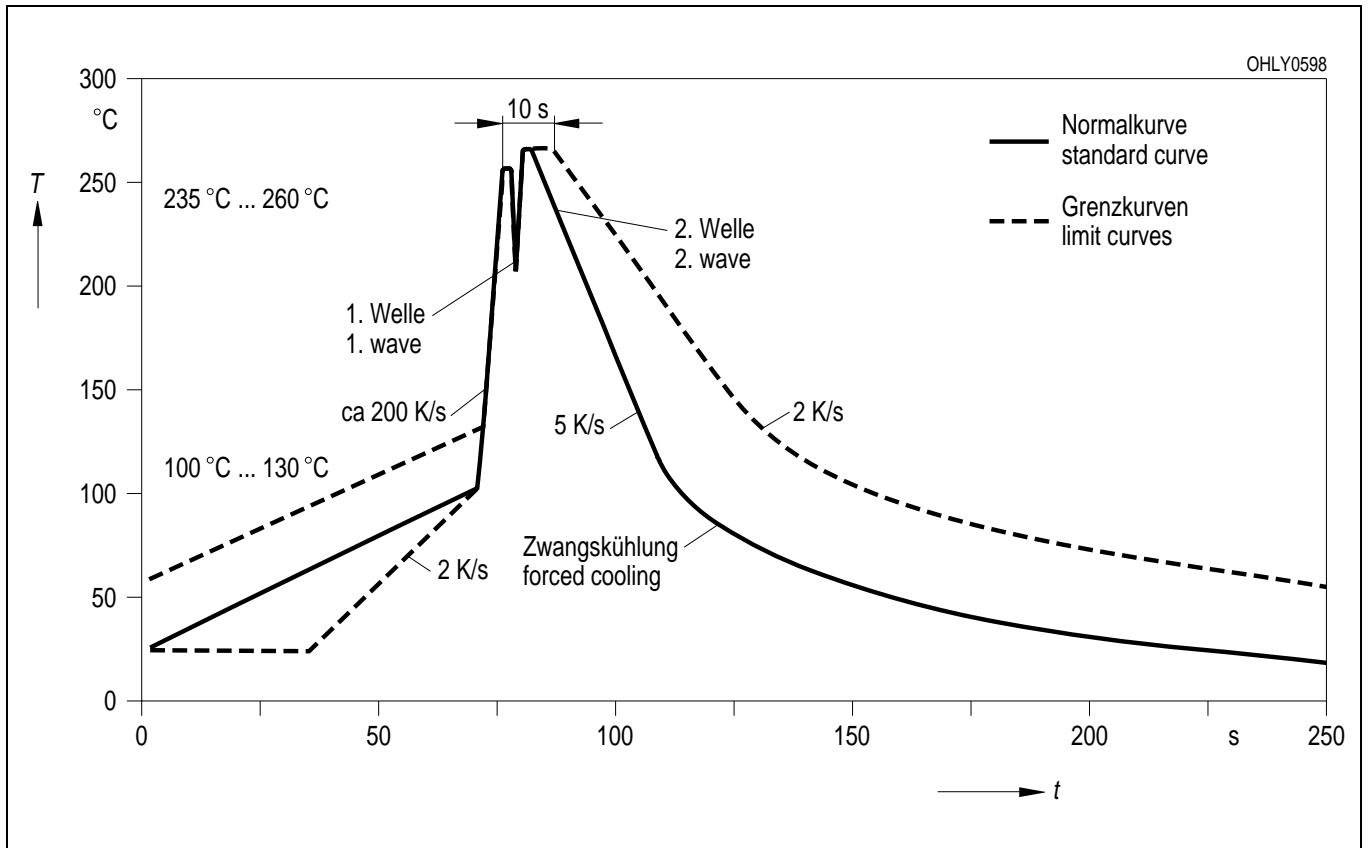


Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

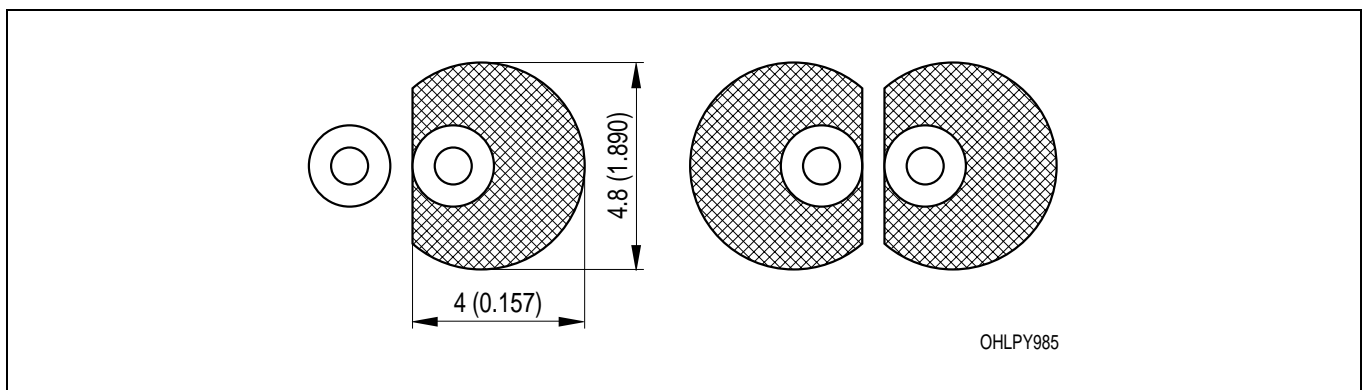
**Kathodenkennung:** kürzerer Lötspieß  
**Cathode mark:** short solder lead  
**Gewicht / Approx. weight:** 0.15 g

**Lötbedingungen**  
**Soldering Conditions**

**Wellenlöten (TTW)** (nach CECC 00802)  
**TTW Soldering** (acc. to CECC 00802)



**Empfohlenes Lötpaddesign** Wellenlöten (TTW)  
**Recommended Solder Pad** TTW Soldering



Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

Revision History: 2003-12-19		Date of change
Previous Version: 2003-06-11		
Page	Subjects (major changes since last revision)	
3	thermal resistance (footnote)	
10	annotations	2002-07-23
5	luminous intensity groups	2002-07-30
3, 4	value (reverse voltage from 5 V to 12 V)	2002-09-18
2	not for new design	2002-09-18
2	removal of single brightness groups	2003-06-11
2	removal of not for new design	2003-12-17

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#### Attention please!

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#### Packing

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